EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	574	333/186	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 19:35
L3	241	333/197	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 19:35
L6	148	333/200	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 19:45
L7	81	257/E23.181	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 19:46
L8	2367	438/125	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 19:47
L9	1865	438/126	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 19:50
S1	5	"5,477,008".pn. or "20040065932" or "20040028849"	US-PGPUB; USPAT	OR	OFF	2008/06/09 07:08

S2	20	(semiconductor or die or dice or chip or IC) and micro near cavity with (seal$3 or hermetica$3)	USPAT	OR	ON	2008/06/09 07:10
S3	18	("4838088" | "5188983" | "5589082" | "5631428" | "5668033" | "5783749" | "5937275" | "5952572" | "6133146" | "6140144" | "6232150" | "6265246" | "6297072" | "6335224" | "6635509").PN. OR ("6902656").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:15
S4	7	("5025346" | "5028983" | "5454158" | "5523619" | "5686697" | "5822856" | "6178093").PN. OR ("6779247").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:15
S5	40	("5589082" | "5668033" | "5783749" | "5937275" | "5952572" | "6140144" | "6232150" | "6265246" | "6297072" | "6335224").PN. OR ("6635509").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:15
S7	6	("5589082" | "5963788" | "6174820" | "6429755" | "6628177" | "6635509").PN. OR ("7002436").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:23
S8	68	("4918032" | "4997521").PN. OR ("5589082").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:31

| S11 | 194 | ("20010001931" \| "20010009110" \| "20010034076" \| "20020016058" \| "20020135047" \| "20040016989" \| "20040065932" \| "4665610" \| "4674319" \| "4766666" \| "4849071" \| "4945769" \| "4990462" \| "5075253" \| "5139624" \| "5156903" \| "5338416" \| "5445991" \| "5455547" \| "5461916" \| "5470797" \| "5491604" \| "5504026" \| "5510156" \| "5517123" \| "5537083" \| "5540095" \| "5583290" \| "5589082" \| "5604312" \| "5613611" \| "5616514" \| "5620931" \| "5627317" \| "5627318" \| "5631422" \| "5640039" \| "5679436" \| "5683591" \| "5703293" \| "5721377" \| "5723353" \| "5728936" \| "5751041" \| "5760455" \| "5761957" \| "5804083" \| "5818227" \| "5839062" \| "5847280" \| "5858809" \| "5872024" \| "5880369" \| "5889207" \| "5898218" \| "5919364" \| "5922212" \| "5937275" \| "5948991" \| "5955932" \| "5959208" \| "5969249" \| "5986316" \| "5987989" \| "5992233" \| "6009753" \| "6028332" \| "6035714" \| "6048774" \| "6055858" \| "6065341" \| "6067858" \| "6090718" \| "6100108" \| "6106735" \| "6117701" \| "6119518" \| "6122964" \| "6125700" \| | US-PGPUB; USPAT; USOCR | OR | OFF | 2008/06/09 07:41 |

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S12	1	"20070126068"	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:52
S13	67	257/E29.324	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 07:56
S14	1497	257/414	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 07:58
S15	1599	257/415	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 07:59
S16	1033	257/417	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 08:11

S17	424	257/418	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 08:28
S18	672	polysilicon with polymer	USPAT	OR	OFF	2008/06/09 08:34
S19	4	polysilicon with polymerized near material	USPAT	OR	OFF	2008/06/09 08:34
S20	27	polysilicon with polymerized	USPAT	OR	OFF	2008/06/09 08:35
S21	3437	polysilicon with glass	USPAT	OR	OFF	2008/06/09 08:38
S22	937	257/419	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 08:41
S23	315	257/420	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 08:49
S24	288	polysilicon near glass	USPAT	OR	OFF	2008/06/09 08:49
S25	5685	257/678	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:01
S26	301	257/619	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:25
S27	0	porous near silicon with photoresis	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:40

S28	72	porous near silicon with photoresist	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:40
S29	2112	438/48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:50
S30	1095	438/50	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:53
S31	0	photoresists with plug same micro near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:54
S32	0	photoresists with plug and micro near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:54
S33	0	photoresists with (plug or cover) and micro near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:55
S34	0	photoresists same (plug or cover) and micro near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:55
S35	4008	photoresist with (silicon near dioxide or alumina)	USPAT	OR	OFF	2008/06/09 09:59
S36	326	photoresist near material with (silicon near dioxide or alumina)	USPAT	OR	OFF	2008/06/09 09:59

S37	1196	438/52	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 10:17
S38	798	(semiconductor or die or dice or chip or IC) and (cavity or open$3 or recess or aperture) with cover$3 and cover$3 with polyimide	USPAT	OR	ON	2008/12/29 22:30
S39	32	(semiconductor or die or dice or chip or IC) and (cavity or open$3 or recess or aperture) with cover$3 and cover$3 with polyimide and mems	USPAT	OR	ON	2008/12/29 22:30
S40	119	257/E29.324	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 22:33
S41	6051	257/678	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 22:33
S42	1614	257/414	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 22:34
S43	4	(semiconductor or die or dice or chip or IC) and (cavity or open$3 or recess or aperture) with cover$3 and cover$3 with (fill$3 or seal$3) with polyimide and mems	USPAT	OR	ON	2008/12/29 22:36
S44	1727	257/415	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 22:46

S45	1076	257/417	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 13:23
S46	322	257/420	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 13:50
S47	870	polysilicon with polymer	USPAT	OR	ON	2008/12/30 13:55
S48	28	polysilicon with made with polymer	USPAT	OR	ON	2008/12/30 13:55
S49	968	257/419	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 14:08
S50	440	257/418	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 14:12
S51	14	polysilicon with part with polymer	USPAT	OR	ON	2008/12/30 14:13
S52	315	257/619	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 14:47
S53	13	(semiconductor or die or dice or chip or IC) and micro near cavity with MEMS	USPAT	OR	ON	2008/12/30 14:51
S54	2312	438/48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 15:17

S55	1188	438/50	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 15:26
S56	92	polymer near polysilicon	USPAT	OR	ON	2008/12/30 16:07
S57	1293	438/52	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 16:14
S58	150	257/e29.324	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 21:24
S59	6294	257/678	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 21:26
S60	1715	257/414	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 21:28
S61	0	(semiconductor or die or dice or chip or IC) and micro near cavity with (seal$3 or cover$3) and plug with (seal$3 or cover$3) and hermetica$3	USPAT	OR	OFF	2009/05/05 21:31
S62	0	(semiconductor or die or dice or chip or IC) and micro near cavity with (seal$3 or cover$3) and plug with (seal$3 or cover$3) and hermetica$3	USPAT	OR	ON	2009/05/05 21:31

S63	4	(semiconductor or die or dice or chip or IC) and micro near cavity with (seal$3 or cover $3) and (open$3 or via or aperture or window) with (seal$3 or cover $3) and hermetica$3	USPAT	OR	ON	2009/05/05 21:31
S64	0	(semiconductor or die or dice or chip or IC) and micro near cavity with (sacrificial) same (seal$3 or cover$3) and (open$3 or via or aperture or window) with (seal$3 or cover $3) and hermetica$3	USPAT	OR	ON	2009/05/05 21:33
S65	0	(semiconductor or die or dice or chip or IC) and micro near cavity with (sacrificial) and (seal$3 or cover$3) and (open$3 or via or aperture or window) with (seal$3 or cover $3) and hermetica$3	USPAT	OR	ON	2009/05/05 21:33
S66	0	(semiconductor or die or dice or chip or IC) and micro near cavity with (sacrific$3) and (seal$3 or cover$3) and (open$3 or via or aperture or window) with (seal$3 or cover $3) and hermetica$3	USPAT	OR	ON	2009/05/05 21:33
S67	4	(semiconductor or die or dice or chip or IC) and micro near cavity and (sacrific$3) and (seal$3 or cover$3) and (open$3 or via or aperture or window) with (seal$3 or cover $3) and hermetica$3	USPAT	OR	ON	2009/05/05 21:33

S68	11	("20040053434" | "20040065932" | "20040126953" | "5329110" | "5597957" | "6274440" | "6582569" | "6590280" | "6636002" | "6787387" | "6924485").PN. OR ("7364932").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/05 21:37
S69	23	("4115719" | "4147929" | "4148050" | "4534099" | "4557037" | "4758734" | "4826777" | "4925805" | "4990827" | "5098856" | "5264693").PN. OR ("5329110").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/05 21:42
S70	14	("2867729" | "3310701" | "3435233" | "3475076" | "3873829" | "3896305").PN. OR ("4147929").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/05 21:44
S71	1810	257/415	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 21:46
S72	258	(semiconductor or die or dice or chip or IC) and cavity and (sacrific $3) and (seal$3 or cover$3) and (open$3 or via or aperture or window) with (seal$3 or cover$3) and hermetica$3	USPAT	OR	ON	2009/05/05 21:46

S73	19	("20020075094" | "20020171517" | "20030047533" | "20030155643" | "20040173886" | "20050074919" | "5090254" | "5589082" | "6118164" | "6133807" | "6444135" | "6452124" | "6452238" | "6472739" | "6621387" | "6635509" | "6673697" | "6686820" | "7102472").PN. OR ("7381583").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/05 21:50
S74	1102	257/417	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 21:54
S75	75	("4918032" | "4997521").PN. OR ("5589082").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/05 21:55
S76	326	257/420	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:00
S77	999	257/419	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:09
S78	445	257/418	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:10
S79	324	257/619	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:12

S80	2438	438/48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:16
S81	1252	438/50	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:19
S82	1355	438/52	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:28
S83	43	("20040219706" | "4990229" | "5242863" | "5397962" | "5448068" | "5486491" | "5493177" | "5550090" | "5593495" | "5640042" | "5694134" | "5801383" | "5886867" | "5891751" | "5921461" | "5929497" | "5990766" | "6060336" | "6074971" | "6093579" | "6117787" | "6135856" | "6258223" | "6262417" | "6284149" | "6294425" | "6377142" | "6377217" | "6377440" | "6404614" | "6440289" | "6492883" | "6514895" | "6525630" | "6534850" | "6535076" | "6543292" | "6547973" | "6556102" | "6570750" | "6590468" | "6593242" | "6597265").PN. OR ("7429495").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/12 17:25
S84	134	photoresists with silicon near nitride	USPAT	OR	OFF	2009/05/12 19:47

S85	0	photoresists near material with silicon near nitride	USPAT	OR	OFF	2009/05/12 19:50
S86	351	photoresists near material with silicon near nitride	USPAT	OR	ON	2009/05/12 19:50
S87	1280	photoresists near material with silicon	USPAT	OR	ON	2009/05/12 19:53
S88	136	photoresists near material near silicon	USPAT	OR	ON	2009/05/12 19:53
S89	29	plug with phosphosilicate near glass	USPAT	OR	ON	2009/05/12 20:36
S90	0	plug near phosphosilicate near glass	USPAT	OR	ON	2009/05/12 20:38
S91	86	plug with (phosphosilicate near glass or "PSG")	USPAT	OR	ON	2009/05/12 20:40
S92	57	S91 not S89	USPAT	OR	ON	2009/05/12 20:40
S93	0	plug near (phosphosilicate near glass or "PSG")	USPAT	OR	ON	2009/05/12 20:41
S94	0	seal$3 with (hole or via or open$3) with phosphosilicate near glass	USPAT	OR	ON	2009/05/12 20:43
S95	5	seal$3 with (hole or via or open$3) and seal$3 with phosphosilicate near glass	USPAT	OR	ON	2009/05/12 20:44
S96	203	257/E29.324	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 13:47
S97	6559	257/678	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 13:47

S98	345	257/619	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 13:48
S99	1820	257/414	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 14:17
S100	1934	257/415	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 14:18
S101	1136	257/417	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 14:26
S102	450	257/418	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 14:49
S103	1054	257/419	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 16:32
S104	2611	438/48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 16:34
S105	1331	438/50	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 16:58

S106	1421	438/52	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 17:25

10/9/09 7:54:02 PM
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